

## OPAx325

### 高精度、10MHz、低ノイズ、低消費電力、RRIO の CMOS オペアンプ

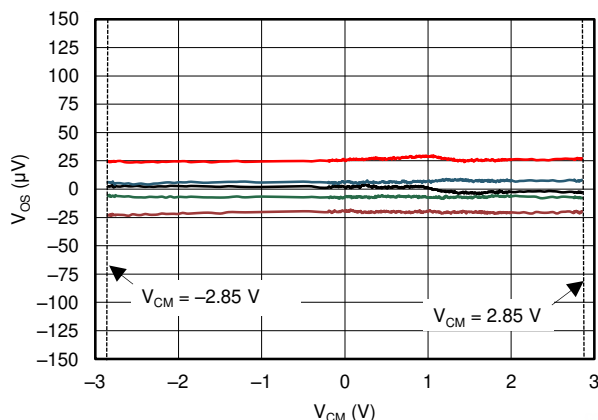
#### 1 特長

- ゼロ・クロスオーバー歪みで高精度
  - 低いオフセット電圧: 150 $\mu$ V (最大値)
  - 高いCMRR: 114dB
  - レール・ツー・レール I/O
- 広い帯域幅: 10MHz
- 静止電流: 650 $\mu$ A/ch
- 単一電源電圧範囲: 2.2~5.5V
- 低い入力バイアス電流: 0.2pA
- 低ノイズ: 9nV/ $\sqrt{\text{Hz}}$  (10kHz 時)
- スルーレート: 5V/ $\mu$ s
- ユニティ・ゲイン安定

#### 2 アプリケーション

- 高インピーダンス・センサの信号コンディショニング
- トランスインピーダンス・アンプ
- 試験および計測機器
- プログラマブル・ロジック・コントローラ (PLC)
- モータ制御ループ
- 通信
- ADC と DAC の入力/出力バッファ
- アクティブ・フィルタ

オフセット電圧 対 入力同相電圧



#### 3 概要

OPA325, OPA2325, OPA4325 (OPAx325) は、超低ノイズで広い帯域幅を提供し、わずか 650 $\mu$ A の低い静止電流で動作するように最適化された高精度、低電圧の CMOS (相補型金属酸化膜半導体) オペアンプです。

OPAx325 はゼロ・クロスオーバー歪みのリニア入力段を特長とし、入力範囲全体で 114dB (標準値) という優れた同相除去比 (CMRR) を実現しています。入力同相範囲は、負および正の電源レールよりも 100mV 拡張されています。出力電圧のスイングは通常、レールから 10mV の範囲内です。

ゼロ・クロスオーバー歪み、広い帯域幅 (10MHz)、高いスルーレート (5V/ $\mu$ s)、低ノイズ (9nV/ $\sqrt{\text{Hz}}$ ) を特長とする OPAx325 は、逐次比較型 (SAR) A/D コンバータ (ADC) の入力ドライバ・アンプとして非常に優れています。また OPA325 は、2.2V~5.5V の広い電源電圧範囲を持ち、電源電圧範囲全体にわたって電源除去比 (PSRR) が優れているため、レギュレーションなしで直接バッテリー動作する高精度、低消費電力アプリケーションに適しています。

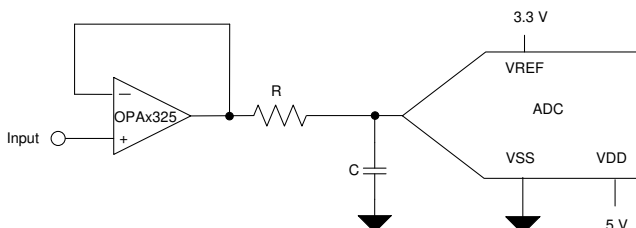
OPA325 (シングル・チャンネル・バージョン) は SOT23-5 パッケージで供給されます。OPA2325 (デュアル・チャンネル・バージョン) は SO-8 および MSOP-8 パッケージで供給されます。OPA4325 (クワッド・チャンネル・バージョン) は TSSOP-14 パッケージで供給されます。

#### 製品情報<sup>(1)</sup>

型番	パッケージ	本体サイズ (公称)
OPA325	SOT-23 (5)	2.90mm×1.60mm
OPA2325	SOIC (8)	4.90mm×3.91mm
	VSSOP (8)	3.00mm×3.00mm
OPA4325	TSSOP (14)	5.00mm×4.40mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にあるパッケージ・オプションについての付録を参照してください。

#### OPAx325 を ADC ドライバ・アンプとして使用する例



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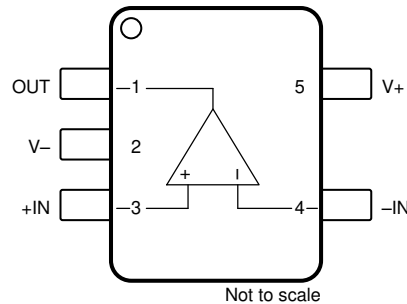
## 4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

<b>Revision C (May 2019) から Revision D に変更</b>	<b>Page</b>
• OPA325 と関連情報をデータシートに 追加 .....	1
<b>Revision B (February 2019) から Revision C に変更</b>	<b>Page</b>
• OPA4325 のステータスをプレビューから量産データ (アクティブ) に 変更 .....	1
<b>Revision A (July 2017) から Revision B に変更</b>	<b>Page</b>
• OPA4325 事前情報デバイスをデータシートに 追加 .....	1
• Added operating temperature to <i>Absolute Maximum Ratings</i> table .....	5
• Deleted specified temperature from <i>Absolute Maximum Ratings</i> table; specified temperature already listed in <i>Recommended Operating Conditions</i> table .....	5
<b>2016年10月発行のものから更新</b>	<b>Page</b>
• デュアル・チャネル・デバイス用の新しい VSSOP パッケージ・オプションを 追加 .....	1
• TI リファレンス・デザインのナビゲータ・アイコンを上端に 追加 .....	1

## 5 Pin Configuration and Functions

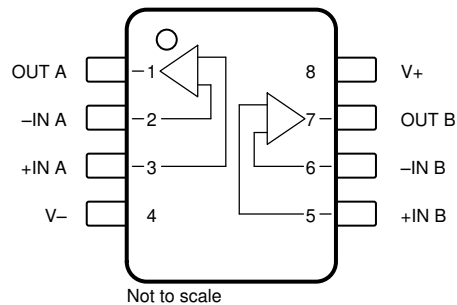
**OPA325: DBV Package  
5-Pin SOT-23  
Top View**



**Pin Functions: OPA325**

PIN		I/O	DESCRIPTION
NAME	NO.		
-IN	4	I	Inverting input
+IN	3	I	Noninverting input
OUT	1	O	Output
V-	2	—	Negative (lowest) power supply
V+	5	—	Positive (highest) power supply

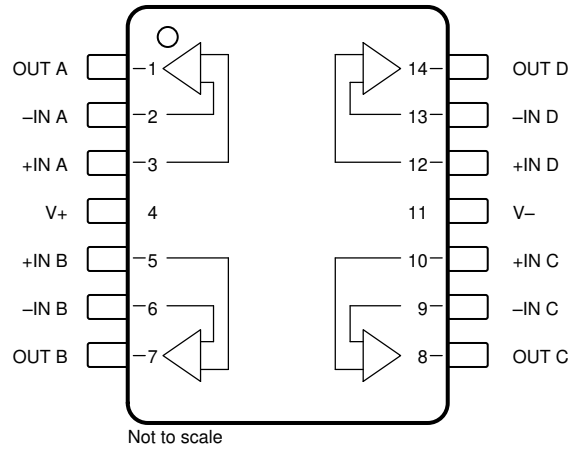
**OPA2325: D and DGK Packages  
8-Pin SOIC, 8-Pin VSSOP  
Top View**



**Pin Functions: OPA2325**

PIN		I/O	DESCRIPTION
NAME	NO.		
-IN A	2	I	Inverting input channel A
+IN A	3	I	Noninverting input channel A
-IN B	6	I	Inverting input channel B
+IN B	5	I	Noninverting input channel B
OUT A	1	O	Output channel A
OUT B	7	O	Output channel B
V-	4	—	Negative supply
V+	8	—	Positive supply

**OPA4325: PW Package  
14-Pin TSSOP  
Top View**



**Pin Functions: OPA4325**

PIN		I/O	DESCRIPTION
NAME	NO.		
-IN A	2	I	Inverting input channel A
+IN A	3	I	Noninverting input channel A
-IN B	6	I	Inverting input channel B
+IN B	5	I	Noninverting input channel B
-IN C	9	I	Inverting input channel C
+IN C	10	I	Noninverting input channel C
-IN D	13	I	Inverting input channel D
+IN D	12	I	Noninverting input channel D
OUT A	1	O	Output channel A
OUT B	7	O	Output channel B
OUT C	8	O	Output channel C
OUT D	14	O	Output channel D
V-	11	—	Negative supply
V+	4	—	Positive supply

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage	$V_S = (V+) - (V-)$		6	V
Signal input pins	Voltage <sup>(2)</sup>	(V-) – 0.5	(V+) + 0.5	V
	Current <sup>(2)</sup>	–10	10	mA
Output short-circuit <sup>(3)</sup>		Continuous		mA
Temperature	Operating, $T_A$	–40	150	°C
	Junction, $T_J$		150	
	Storage, $T_{stg}$	–65	150	

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) Input pins are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5 V beyond the supply rails must be current limited to 10 mA or less.
- (3) Short-circuit to ground, one amplifier per package.

### 6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±4000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
$V_S$	Supply voltage	Single supply	2.2		5.5	V
		Dual supply	±1.1		±2.75	
$T_A$	Specified temperature		–40		125	°C

#### 6.4 Thermal Information: OPA325

THERMAL METRIC <sup>(1)</sup>		OPA325	
		DBV (SOT)	
		5 PINS	
			UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	205	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	200	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	113	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	38.2	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	104.9	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

#### 6.5 Thermal Information: OPA2325

THERMAL METRIC <sup>(1)</sup>		OPA2325		UNIT
		D (SOIC)	DGK (VSSOP)	
		8 PINS	8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	119	143	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	60	47	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	61	64	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	15.0	5.3	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	60.4	62.8	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

#### 6.6 Thermal Information: OPA4325

THERMAL METRIC <sup>(1)</sup>		OPA4325	
		PW (TSSOP)	
		14 PINS	
			UNIT
$R_{\theta JA}$	Junction-to-ambient thermal resistance	93	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	28	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	34	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	1.9	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	33.1	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics application report](#).

## 6.7 Electrical Characteristics: $V_S = 2.2\text{ V to }5.5\text{ V}$ or $\pm 1.1\text{ V to } \pm 2.75\text{ V}$

at  $T_A = 25^\circ\text{C}$ ,  $R_L = 10\text{ k}\Omega$  connected to  $V_S / 2$ ,  $V_{CM} = V_S / 2$ , and  $V_{OUT} = V_S / 2$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OFFSET VOLTAGE</b>						
$V_{OS}$	Input offset voltage			40	150	$\mu\text{V}$
$dV_{OS}/dT$	Input offset voltage drift	$V_S = 5.5\text{ V}$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$		2	7.5	$\mu\text{V}/^\circ\text{C}$
PSRR	Power-supply rejection ratio	$V_S = 2.2\text{ V to } +5.5\text{ V}$		6	20	$\mu\text{V/V}$
		$V_S = 2.2\text{ V to } 5.5\text{ V}$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$		15		
	Channel separation	At 1 kHz		130		dB
<b>INPUT VOLTAGE</b>						
$V_{CM}$	Common-mode voltage range		$(V-) - 0.1$		$(V+) + 0.1$	V
CMRR	Common-mode rejection ratio	$V_S = 5.5\text{ V}$ , $(V-) - 0.1\text{ V} < V_{CM} < (V+) + 0.1\text{ V}$	100	114		dB
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$	95			
<b>INPUT BIAS CURRENT</b>						
$I_B$	Input bias current			$\pm 0.2$	$\pm 10$	$\text{pA}$
		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$			$\pm 500$	
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$				$\pm 10$
$I_{OS}$	Input offset current			$\pm 0.2$	$\pm 10$	$\text{pA}$
		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$			$\pm 500$	
		$T_A = -40^\circ\text{C to } +125^\circ\text{C}$				$\pm 10$
<b>NOISE</b>						
	Input voltage noise	$f = 0.1\text{ Hz to } 10\text{ Hz}$		2.8		$\mu\text{V}_{PP}$
$e_n$	Input voltage noise density	$f = 1\text{ kHz}$		10		$\text{nV}/\sqrt{\text{Hz}}$
		$f = 10\text{ kHz}$		9		
$i_n$	Input current noise density	$f = 1\text{ kHz}$		1.3		$\text{fA}/\sqrt{\text{Hz}}$
<b>INPUT CAPACITANCE</b>						
	Differential			5		pF
	Common-mode			4		pF
<b>OPEN-LOOP GAIN</b>						
$A_{OL}$	Open-loop voltage gain	$0.1\text{ V} < V_O < (V+) - 0.1\text{ V}$ , $R_L = 10\text{ k}\Omega$	105	130		dB
		$0.1\text{ V} < V_O < (V+) - 0.1\text{ V}$ , $R_L = 10\text{ k}\Omega$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$	95	128		
		$0.2\text{ V} < V_O < (V+) - 0.2\text{ V}$ , $R_L = 2\text{ k}\Omega$	100	110		
PM	Phase margin	$G = 1\text{ V/V}$ , $V_S = 5\text{ V}$ , $C_L = 15\text{ pF}$		67		Degrees
<b>FREQUENCY RESPONSE (<math>V_S = 5.0\text{ V}</math>, <math>C_L = 50\text{ pF}</math>)</b>						
GBP	Gain bandwidth product	Unity gain		10		MHz
SR	Slew rate	$G = +1$		5		$\text{V}/\mu\text{s}$
$t_S$	Settling time	To 0.1%, 2-V step, $G = +1$		0.6		$\mu\text{s}$
		To 0.01%, 2-V step, $G = +1$		1		
	Overload recovery time	$V_{IN} \times G > V_S$		200		ns
THD+N	Total harmonic distortion + noise <sup>(1)</sup>	$V_O = 4\text{ V}_{PP}$ , $G = +1$ , $f = 10\text{ kHz}$ , $R_L = 10\text{ k}\Omega$		0.0005%		
		$V_O = 2\text{ V}_{PP}$ , $G = +1$ , $f = 10\text{ kHz}$ , $R_L = 600\ \Omega$		0.005%		

(1) Third-order filter; bandwidth = 80 kHz at -3 dB.

**Electrical Characteristics:  $V_S = 2.2\text{ V to }5.5\text{ V}$  or  $\pm 1.1\text{ V to } \pm 2.75\text{ V}$  (continued)**

 at  $T_A = 25^\circ\text{C}$ ,  $R_L = 10\text{ k}\Omega$  connected to  $V_S / 2$ ,  $V_{CM} = V_S / 2$ , and  $V_{OUT} = V_S / 2$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OUTPUT</b>						
$V_O$	Voltage output swing from both rails	$R_L = 10\text{ k}\Omega$		10	20	mV
		$R_L = 10\text{ k}\Omega$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$			30	
		$R_L = 2\text{ k}\Omega$		25	45	
		$R_L = 2\text{ k}\Omega$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$			55	
$I_{SC}$	Short-circuit current	$V_S = 5.5\text{ V}$	See the <a href="#">Typical Characteristics</a>			mA
$C_L$	Capacitive load drive		See the <a href="#">Typical Characteristics</a>			
$R_O$	Open-loop output resistance	$I_O = 0\text{ mA}$ , $f = 1\text{ MHz}$		180		$\Omega$
<b>POWER SUPPLY</b>						
$I_Q$	Quiescent current per amplifier	$I_O = 0\text{ mA}$ , $V_S = 5.5\text{ V}$		0.65	0.75	mA
		$I_O = 0\text{ mA}$ , $V_S = 5.5\text{ V}$ , $T_A = -40^\circ\text{C to } +125^\circ\text{C}$			0.8	
	Power-on time	$V_+ = 0\text{ V to } 5\text{ V}$ , to 90% $I_Q$ level		28		$\mu\text{s}$

### 6.8 Typical Characteristics

at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{midsupply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)

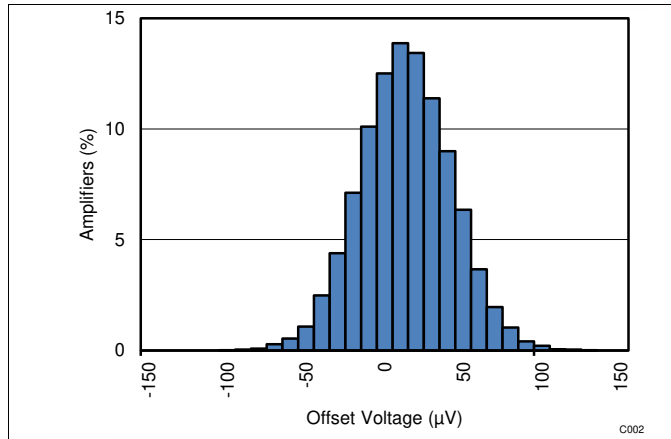


Fig 1. Offset Voltage Production Distribution Histogram

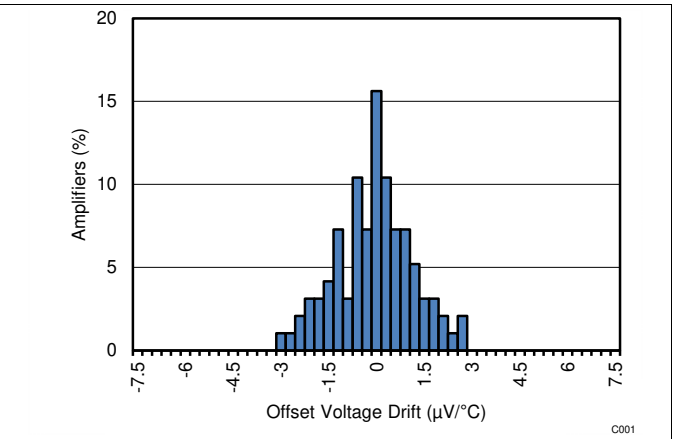


Fig 2. Offset Voltage Drift Distribution Histogram

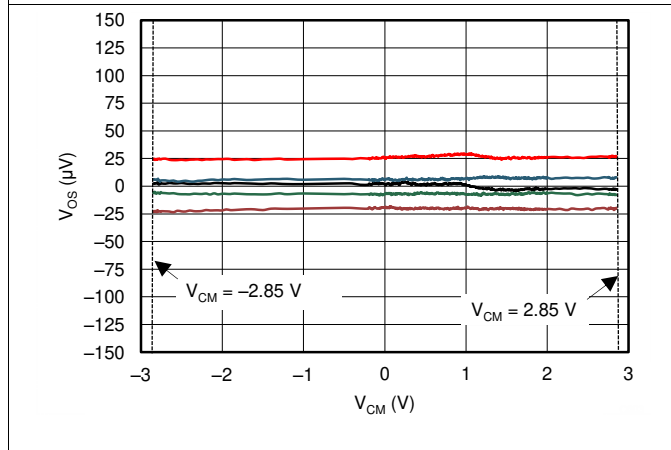


Fig 3. Offset Voltage vs Common-Mode Voltage

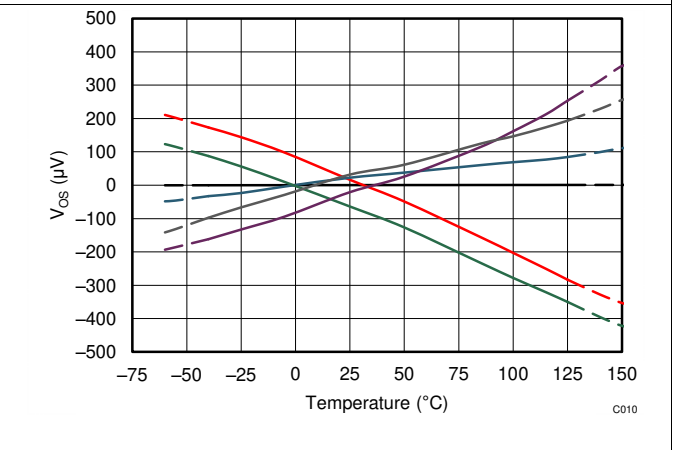


Fig 4. Offset Voltage vs Temperature

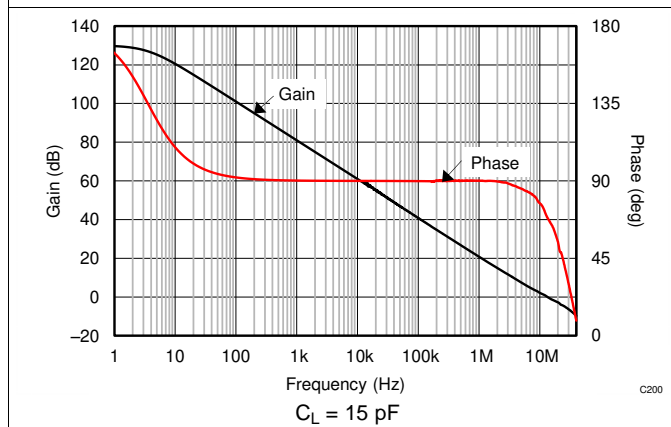


Fig 5. Open-Loop Gain and Phase vs Frequency

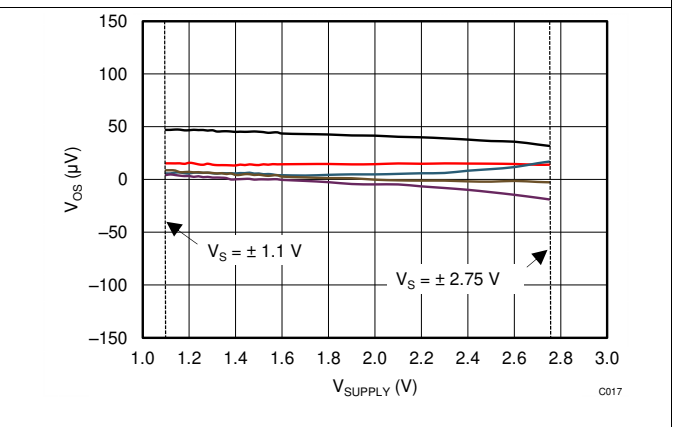
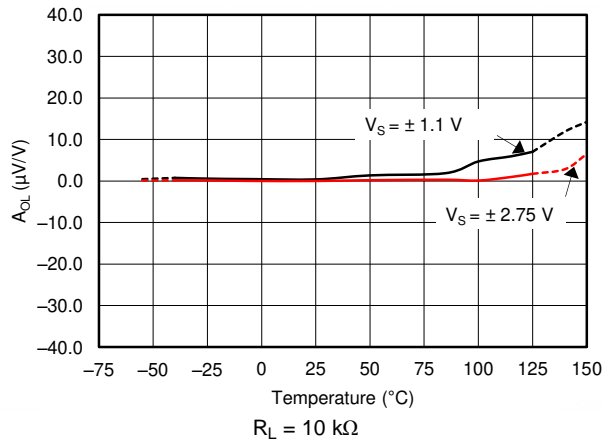


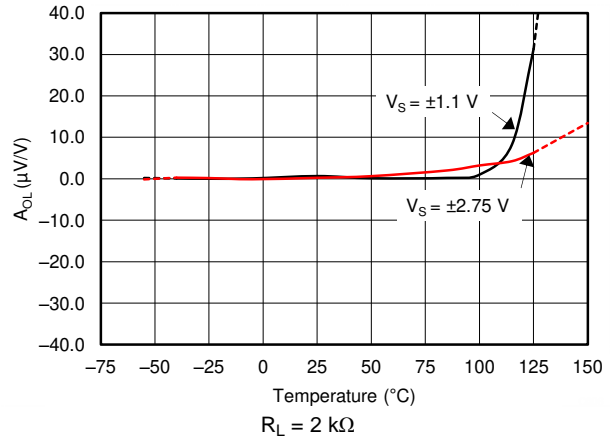
Fig 6. Offset Voltage vs Supply Voltage

**Typical Characteristics (continued)**

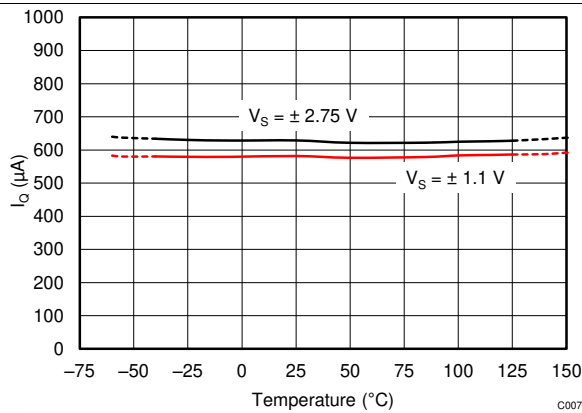
at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{midsupply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



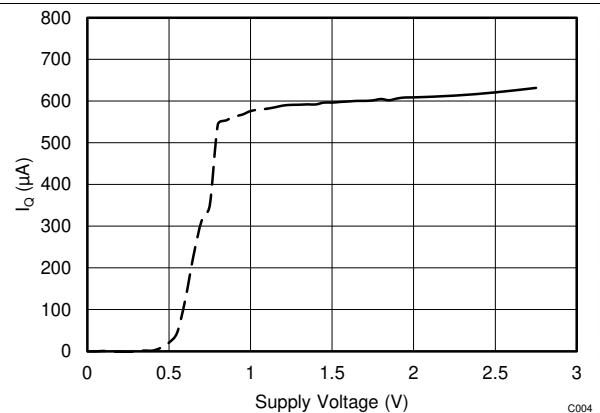
**图 7. Open-Loop Gain vs Temperature**



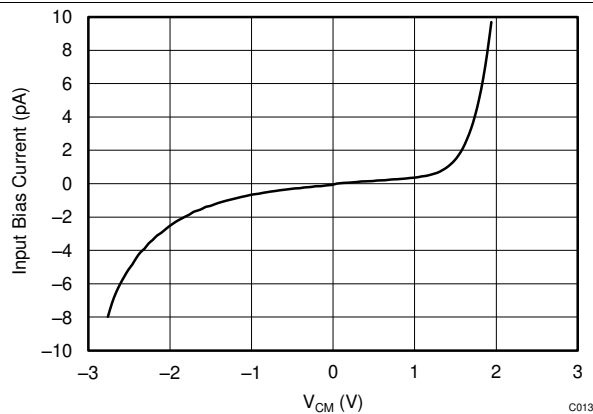
**图 8. Open-Loop Gain vs Temperature**



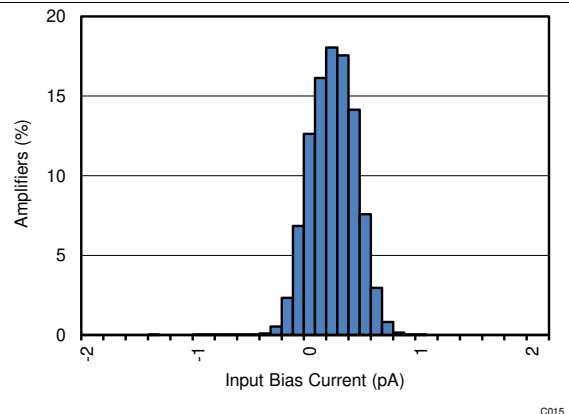
**图 9. Quiescent Current vs Temperature**



**图 10. Quiescent Current vs Supply Voltage**



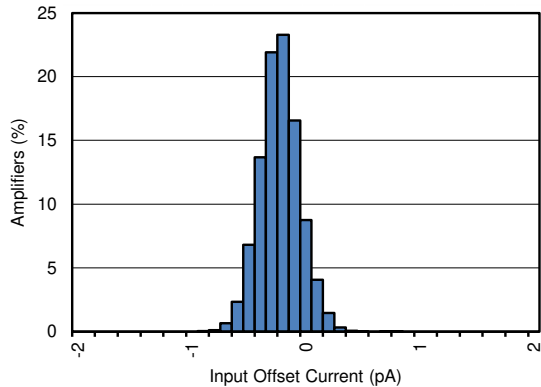
**图 11. Input Bias Current vs Common-Mode Voltage**



**图 12. Input Bias Current Distribution Histogram**

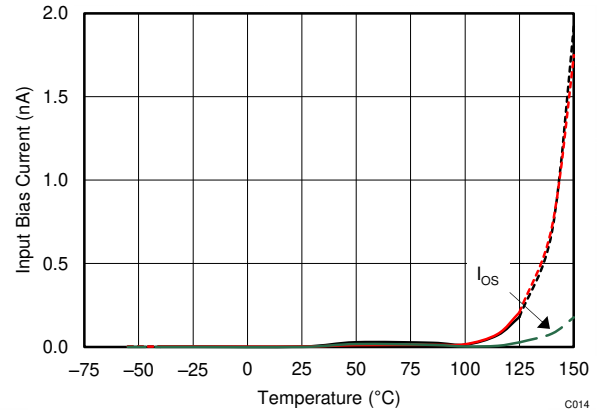
**Typical Characteristics (continued)**

at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{midsupply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



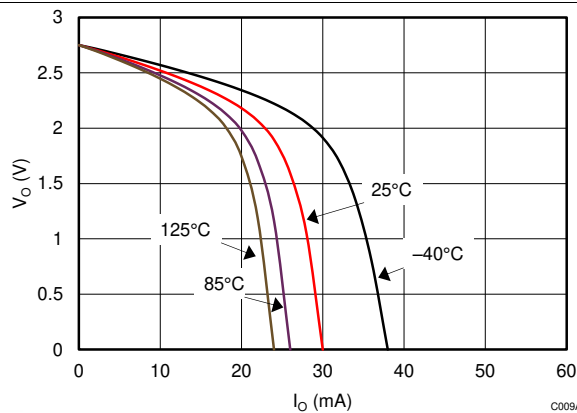
C016

图 13. Input Offset Current Distribution Histogram



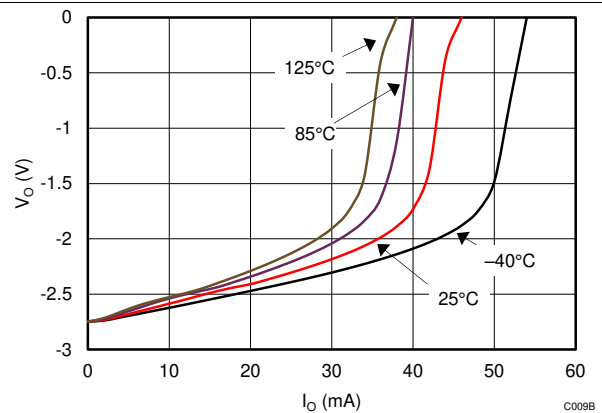
C014

图 14. Input Bias Current vs Temperature



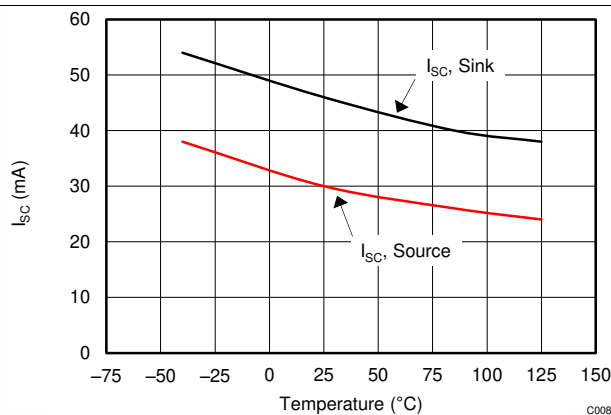
C009A

图 15. Output Voltage Swing (Positive) vs Output Current



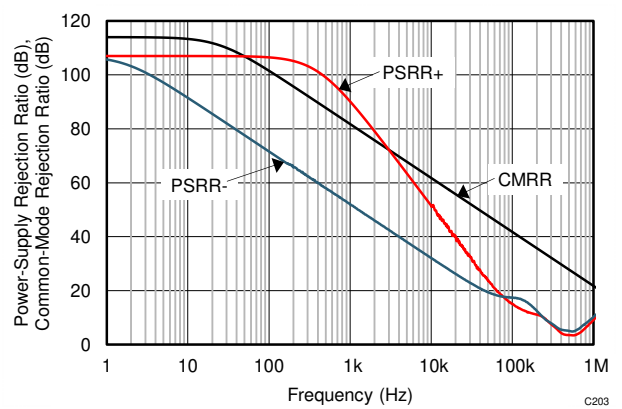
C009B

图 16. Output Voltage Swing (Negative) vs Output Current



C008

图 17. Short-Circuit Current vs Temperature

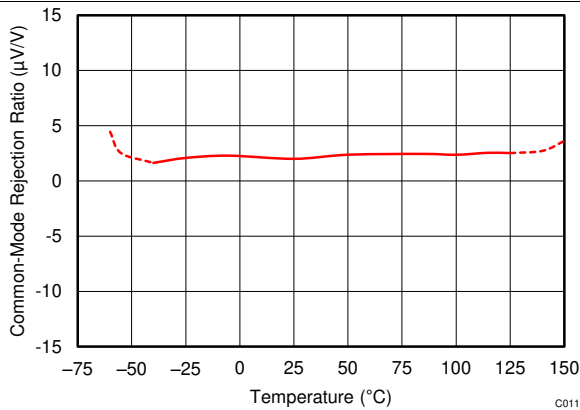


C203

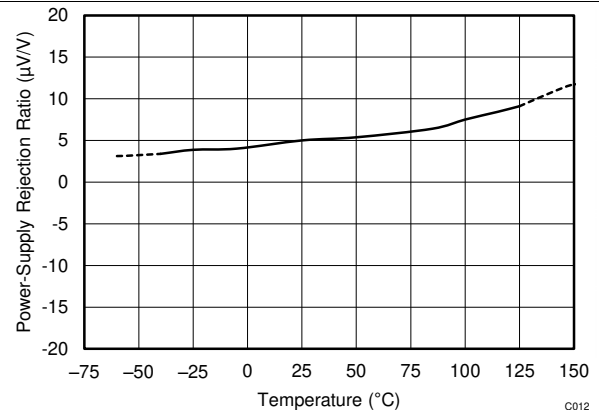
图 18. CMRR and PSRR vs Frequency

Typical Characteristics (continued)

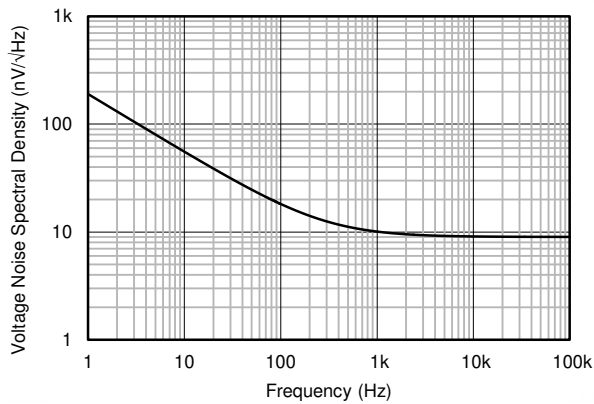
at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{mid supply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



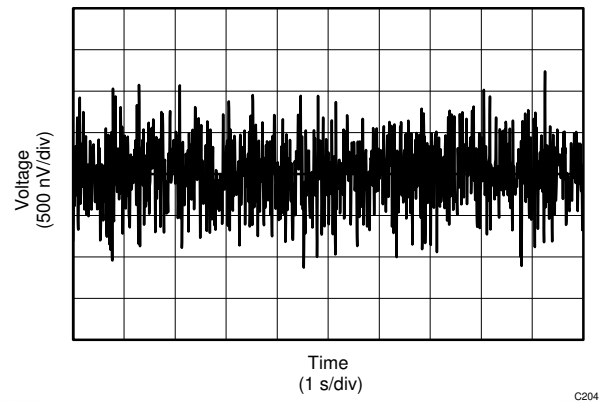
19. CMRR vs Temperature



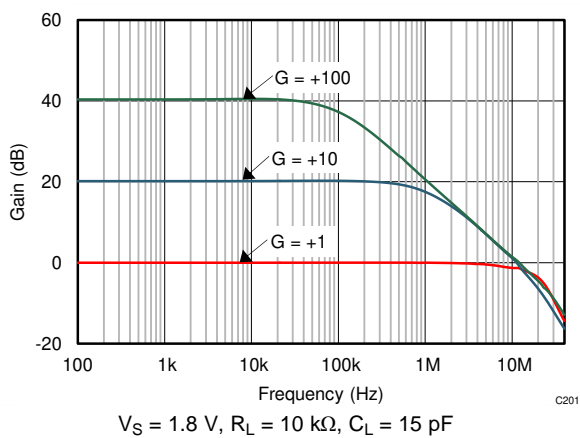
20. PSRR vs Temperature



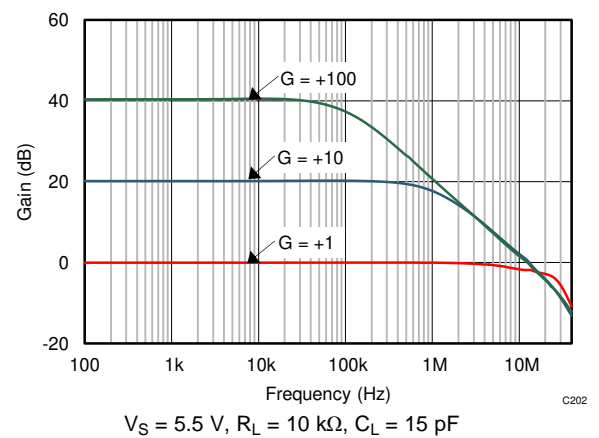
21. Input Voltage Noise Spectral Density vs Frequency



22. 0.1-Hz to 10-Hz Input Voltage Noise



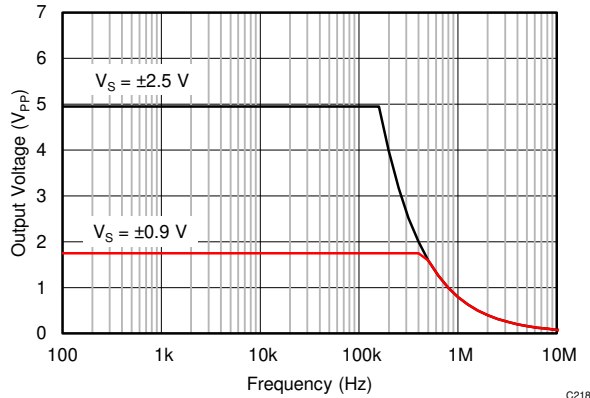
23. Closed-Loop Gain vs Frequency



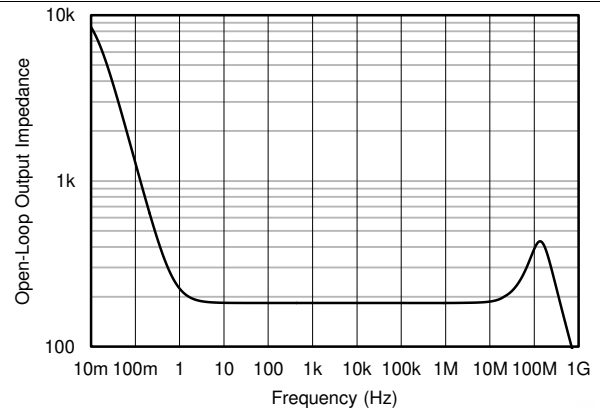
24. Closed-Loop Gain vs Frequency

Typical Characteristics (continued)

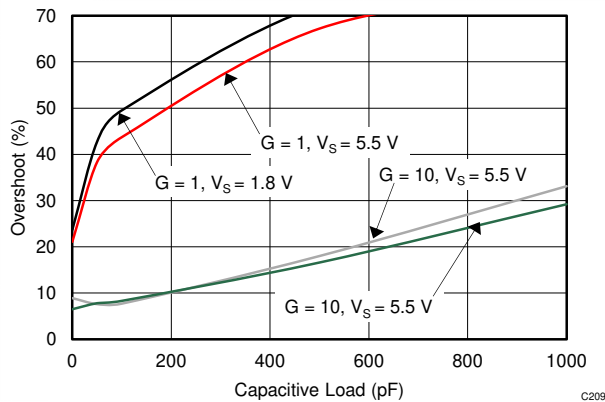
at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{midsupply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



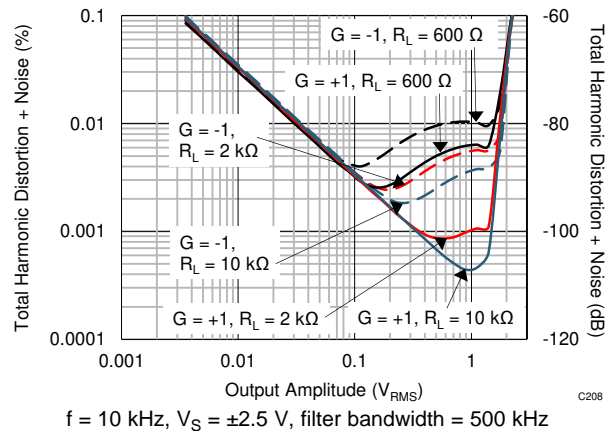
25. Maximum Output Voltage vs Frequency



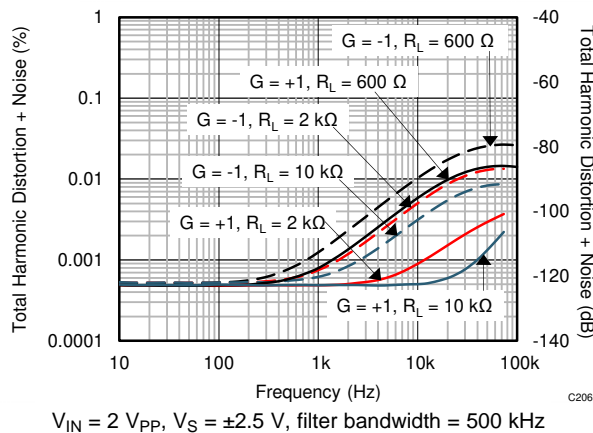
26. Open-Loop Output Impedance vs Frequency



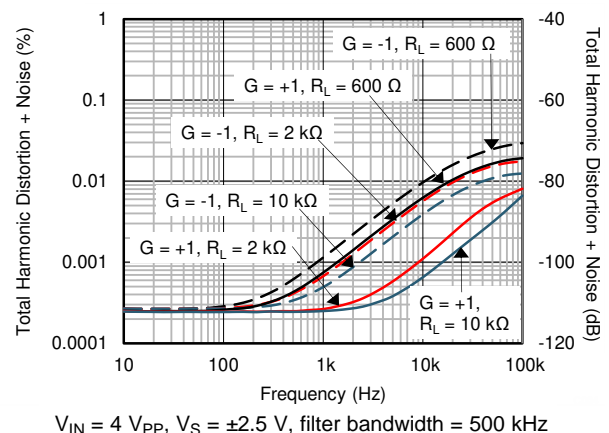
27. Small-Signal Overshoot vs Load Capacitance



28. THD+N vs Amplitude



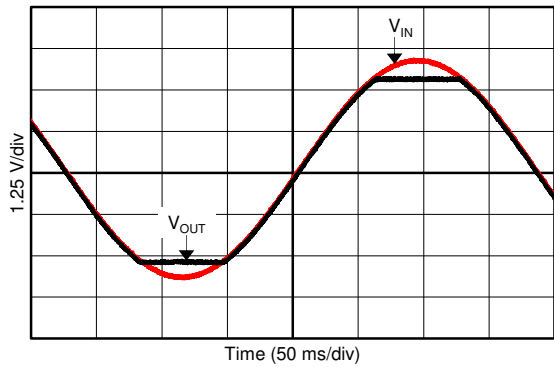
29. THD+N vs Frequency



30. THD+N vs Frequency

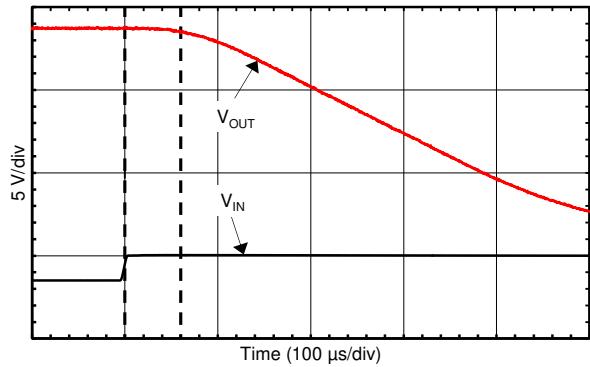
Typical Characteristics (continued)

at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{mid supply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



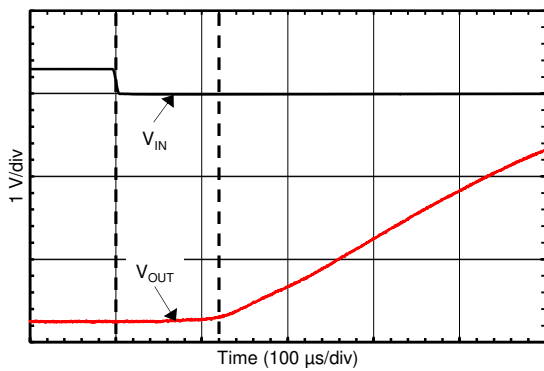
C210

31. No Phase Reversal



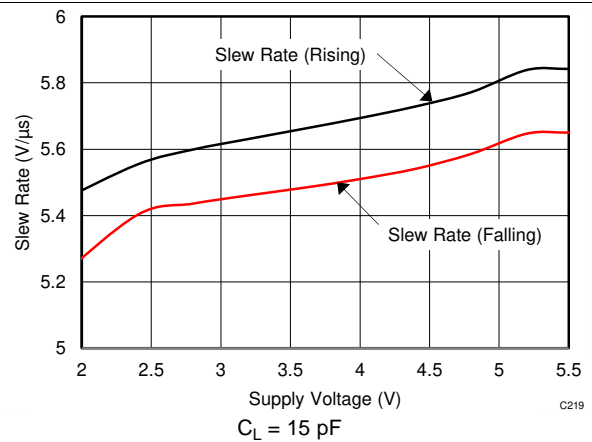
C212

32. Positive Overload Recovery



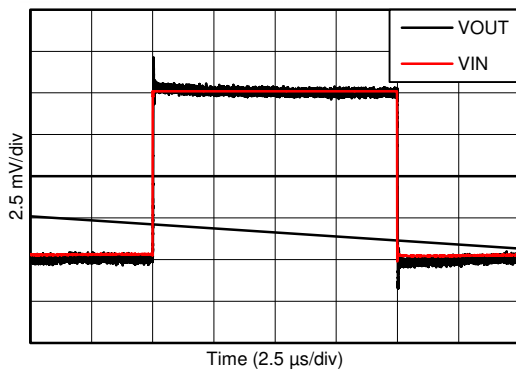
C211

33. Negative Overload Recovery



C219

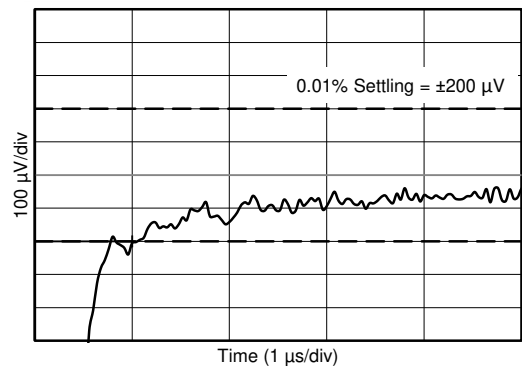
34. Slew Rate vs Supply Voltage



C213

$V_{IN} = 10\text{ mV}_{PP}$ ,  $G = +1$ ,  $C_L = 15\text{ pF}$

35. Small-Signal Step Response



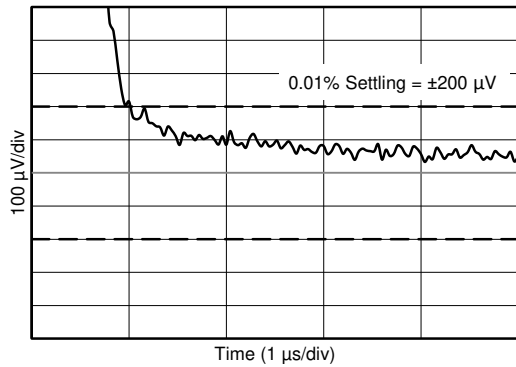
C217

$V_{IN} = 2\text{-V step}$

36. 0.01% Positive Settling Time

**Typical Characteristics (continued)**

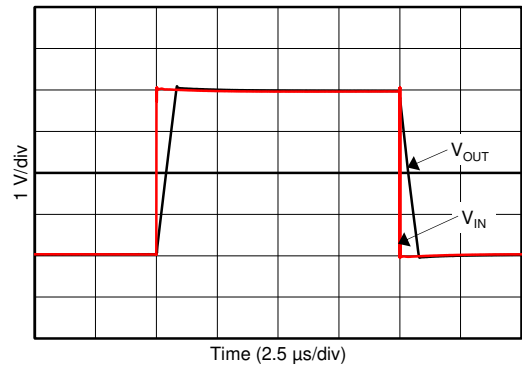
at  $T_A = 25^\circ\text{C}$ ,  $V_{CM} = V_{OUT} = \text{midsupply}$ , and  $R_L = 10\text{ k}\Omega$  (unless otherwise noted)



$V_{IN} = 2\text{-V step}$

C216

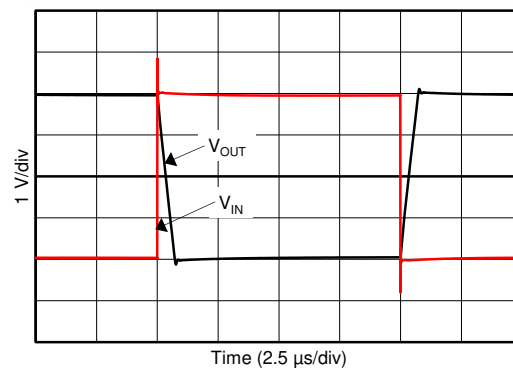
**37. 0.01% Negative Settling Time**



$V_{IN} = 4\text{ V}_{PP}$ ,  $G = +1$ ,  $C_L = 15\text{ pF}$

C215

**38. Large-Signal Step Response**



$V_{IN} = 4\text{ V}_{PP}$ ,  $G = -1$ ,  $C_L = 15\text{ pF}$

C214

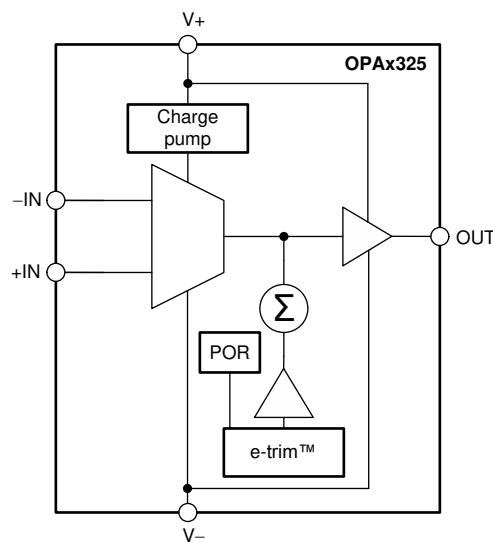
**39. Large-Signal Step Response**

## 7 Detailed Description

### 7.1 Overview

The OPA325, OPA2325, and OPA4325 (OPAx325) belong to a new generation of low-noise, e-trim™ operational amplifiers that provide outstanding dc precision. The OPAx325 also have a highly linear input stage with zero-crossover distortion that delivers excellent CMRR and distortion performance across the full rail-to-rail input range. In addition, this device has a wide supply range with excellent PSRR. This feature, combined with low quiescent current, makes the OPAx325 an excellent choice for applications that are battery-powered without regulation.

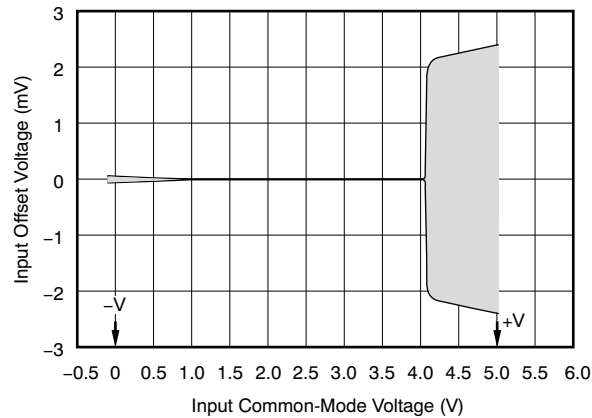
### 7.2 Functional Block Diagram



### 7.3 Feature Description

#### 7.3.1 Zero-Crossover Input Stage

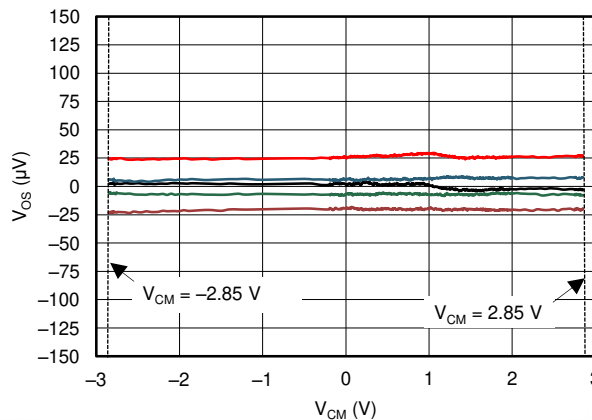
Traditional complementary metal-oxide semiconductor (CMOS) rail-to-rail input amplifiers use a complementary input stage: an N-channel input differential pair in parallel with a P-channel differential pair. This configuration results in sudden change in offset voltage when the input stage transitions from the p-channel metal-oxide-semiconductor field effect transistor (PMOS) to the n-type field effect transistor (NMOS), or vice-versa, as shown in [Figure 40](#). This transition results in significant degradation of CMRR and PSRR performance of the amplifier.



**Figure 40. Input Common-Mode Voltage vs Input Offset Voltage (Traditional Rail-to-Rail Input CMOS Amplifiers)**

The OPAx325 series of amplifiers includes an internal charge pump that powers the amplifier input stage with an internal supply rail that is higher than the external power supply. The internal supply rail allows a single differential pair to operate and to be linear across the entire input common-mode voltage range, thus eliminating crossover distortion. Rail-to-rail amplifiers that use this technique to eliminate crossover distortion are called *zero-crossover amplifiers*.


The single differential pair combined with the charge pump allows the OPAx325 to provide superior CMRR across the entire common-mode input range, which extends 100 mV beyond both power-supply rails. [Figure 41](#) shows the input offset voltage versus input common-mode voltage plot for the OPAx325. Note that unlike traditional rail-to-rail CMOS amplifiers, there is no transition region for the OPAx325.

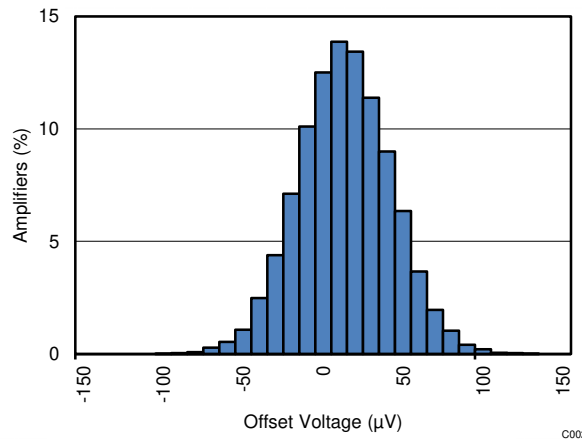


**Figure 41. Offset Voltage vs Common-Mode Voltage (Zero-Crossover)**

## Feature Description (continued)


### 7.3.2 Low Input Offset Voltage

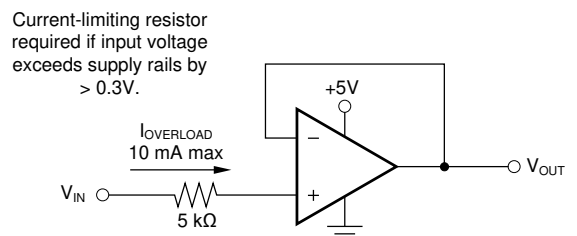
The OPAx325 are manufactured using TI's e-trim technology. Each amplifier is trimmed in production, thereby minimizing errors associated with input offset voltage. The e-trim technology is a TI proprietary method of trimming internal device parameters during either wafer probing or final testing. This process allows the OPAx325 to have an excellent offset specification of 150  $\mu\text{V}$  (maximum).  42 shows the offset voltage distribution for the OPAx325.



 42. Offset Voltage Distribution

### 7.3.3 Input and ESD Protection

The OPAx325 incorporate internal electrostatic discharge (ESD) protection circuits on all pins. In the case of input and output pins, this protection primarily consists of current-steering diodes connected between the input and power-supply pins. These ESD protection diodes also provide in-circuit, input overdrive protection, as long as the current is limited to 10 mA as stated in the *Absolute Maximum Ratings* table.  43 shows how a series input resistor can be added to the driven input to limit the input current. The added resistor contributes thermal noise at the amplifier input; thus, keep the value to a minimum in noise-sensitive applications.



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 43. Input Current Protection

## 7.4 Device Functional Modes

The OPAx325 have a single functional mode and are operational when the power-supply voltage is greater than 2.2 V ( $\pm 1.1$  V). The maximum power-supply voltage for the OPAx325 is 5.5 V ( $\pm 2.75$  V).

## 8 Application and Implementation

### 注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 8.1 Application Information

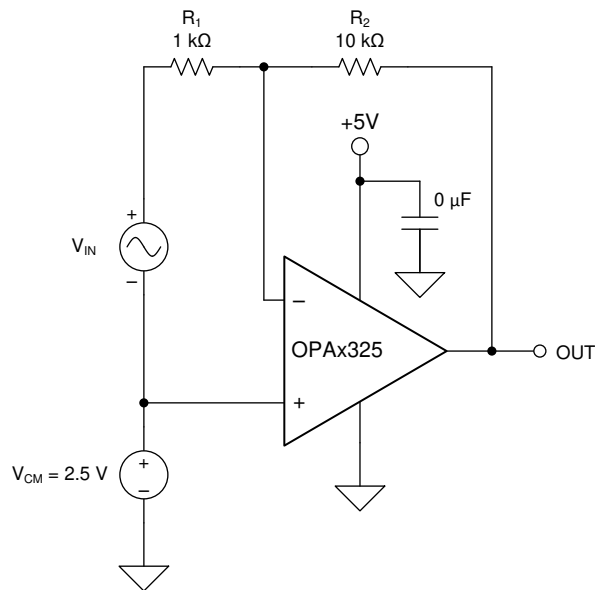
The OPAx325 series features e-trim, a proprietary technique in which the offset voltage is adjusted during the final steps of manufacturing. As a result, the OPAx325 deliver excellent offset voltage (40  $\mu$ V, typical). Additionally, the amplifier boasts a fast slew rate, low drift, low noise, and excellent PSRR and  $A_{OL}$ . The OPAx325 also feature a linear input stage with zero-crossover distortion, resulting in excellent CMRR over the entire input range, which extends from 100 mV below the negative rail to 100 mV above the positive rail.

#### 8.1.1 Operating Characteristics

The OPAx325 family of amplifiers has parameters that are fully specified from 2.2 V to 5.5 V ( $\pm 1.1$  V to  $\pm 2.75$  V). Many of the specifications apply from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the [Typical Characteristics](#) section.

#### 8.1.2 Basic Amplifier Configurations

The OPAx325 are unity-gain stable. The devices do not exhibit output phase inversion when the input is overdriven. A typical single-supply connection is shown in [Figure 44](#). The OPAx325 are configured as a basic inverting amplifier with a gain of  $-10$  V/V. This single-supply connection has an output centered on the common-mode voltage,  $V_{CM}$ . For the circuit shown, this voltage is 2.5 V, but can be any value within the common-mode input voltage range.



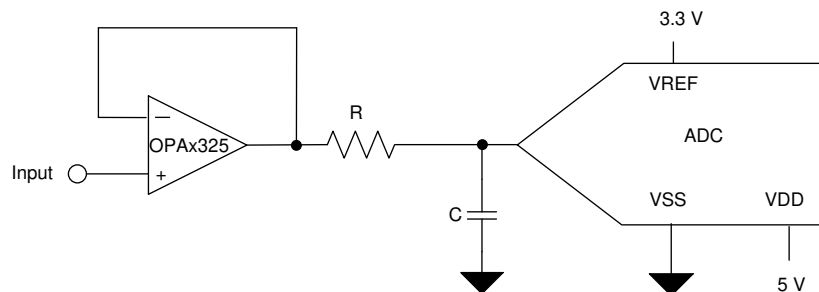
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**Figure 44. Basic Single-Supply Connection**

## Application Information (continued)

### 8.1.3 Driving an Analog-to-Digital Converter

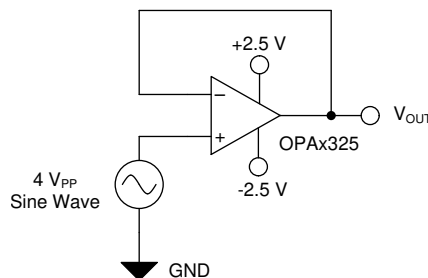
The low-noise and wide-gain bandwidth of the OPAx325, combined with rail-to-rail input/output and zero-crossover distortion, make these devices an excellent input driver for ADCs. [Figure 45](#) shows the OPAx325 driving an ADC. The amplifier is connected as a unity-gain, noninverting buffer.



**Figure 45. The OPAx325 as an Input Driver for ADCs**

## 8.2 Typical Application

Operational amplifiers are commonly used as unity-gain buffers. [Figure 46](#) shows the schematic for an amplifier configured as a unity-gain buffer. If the input signal range to the amplifier is very close to the rails or includes the rails, a rail-to-rail amplifier must be used. However, regular rail-to-rail amplifiers introduce significant distortion to the signal. This design compares the distortion introduced by a typical CMOS input amplifier with that of the OPAx325 (a zero-crossover amplifier).



**Figure 46. The OPAx325 Configured as a Unity-Gain Buffer Amplifier**

### 8.2.1 Design Requirements

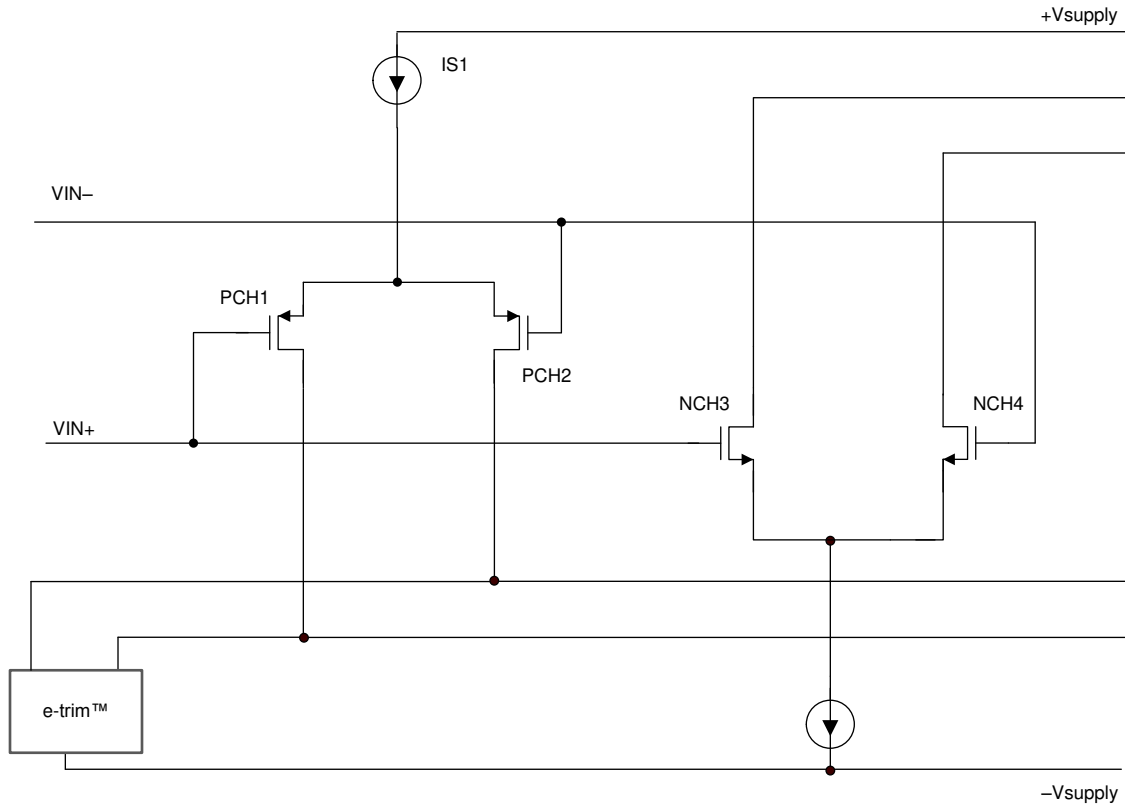
The following parameters are used for this design example:

- Gain = +1 V/V (inverting gain)
- $V_+ = 2.5\text{ V}$ ,  $V_- = -2.5\text{ V}$
- Input signal =  $4\text{ V}_{PP}$ ,  $f = 1\text{-kHz}$  sine wave

## Typical Application (continued)

### 8.2.2 Detailed Design Procedure

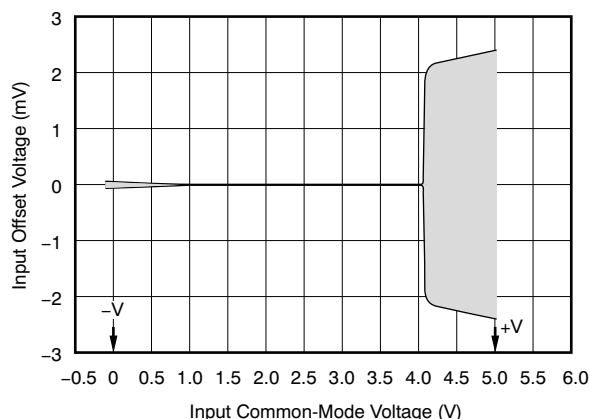
Traditional CMOS rail-to-rail input amplifiers use a complementary input stage: an N-channel input differential pair in parallel with a P-channel differential pair, as shown in [Figure 47](#).



**Figure 47. Complementary Input Stage (Traditional Rail-to-Rail Input CMOS Amplifiers)**

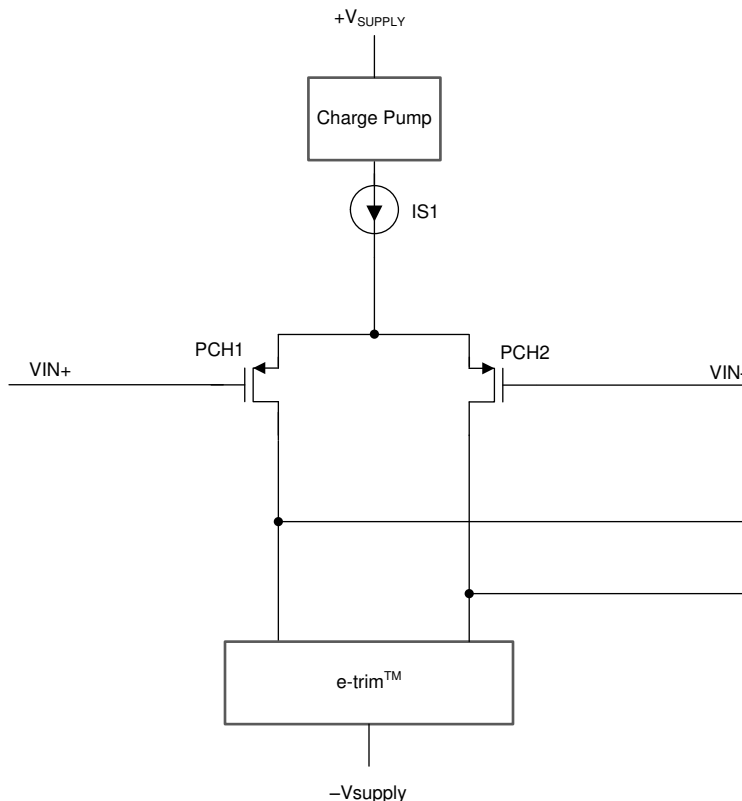
### Typical Application (continued)

The N-channel pair is active for input voltages close to the positive rail, typically  $(V+) - 1\text{ V}$  to 200 mV above the positive supply, and the P-channel pair is on for inputs from 200 mV below the negative supply to approximately  $(V+) - 1\text{ V}$ . There is a small transition region, typically  $(V+) - 1.1\text{ V}$  to  $(V+) - 0.9\text{ V}$ , in which both pairs are on. This transition region is shown in [Figure 48](#) for a traditional rail-to-rail input CMOS amplifier. Within this transition region, PSRR, CMRR, offset voltage, offset drift, and THD can be degraded when compared to device operation outside of this region.



**Figure 48. Input Offset Voltage vs Common-Mode Voltage (For Traditional Rail-to-Rail Input CMOS Amplifiers)**

The OPAx325 amplifiers include an internal charge pump that powers the amplifier input stage with an internal supply rail that is higher than the external power supply. The internal supply rail allows a single differential pair to operate and to be linear across the entire input common-mode voltage range, as shown in [Table 1](#).



**Figure 49. Single Differential Input Pair with a Charge Pump (Zero-Crossover)**

### Typical Application (continued)

The unique zero-crossover topology shown in 表 1 eliminates the input offset transition region, typical of most rail-to-rail input operational amplifiers. This topology allows the OPAx325 to provide superior CMRR across the entire common-mode input range that extends 100 mV beyond both power-supply rails. 图 50 shows the input offset voltage versus input common-mode voltage plot for the OPAx325.

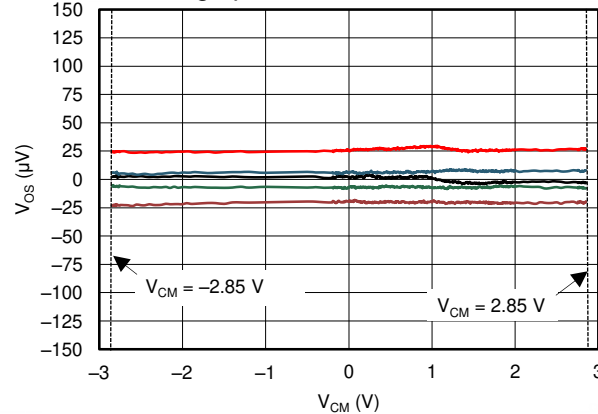


图 50. Offset Voltage vs Common-Mode Voltage (OPAx325, Zero-Crossover Amplifier)

The OPAx325 and a typical CMOS amplifier were used in identical circuits where these amplifiers were configured as a unity-gain buffer amplifier; see 图 51 and 图 52. A pure sine wave with an amplitude of 2 V (4 V<sub>PP</sub>) was given as input to the two identical circuits of 图 51 and 图 52. The outputs of these circuits were captured on a spectrum analyzer. 图 53 and 图 54 illustrate the output voltage spectrum for the OPAx325 and a typical CMOS rail-to-rail amplifier, respectively. The output of the OPAx325 has very few spurs and harmonics when compared to the typical rail-to-rail CMOS amplifier, as illustrated in 图 55.

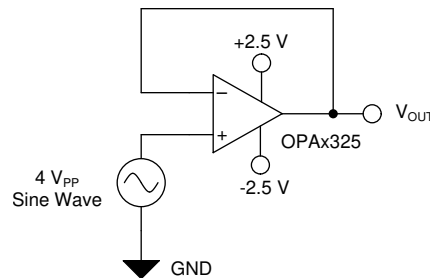


图 51. OPAx325 as a Unity-Gain Buffer

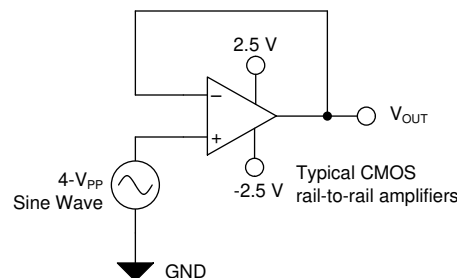


图 52. Typical CMOS Rail-to-Rail Amplifier as a Unity-Gain Buffer

**Typical Application (continued)**

**8.2.3 Application Curves**

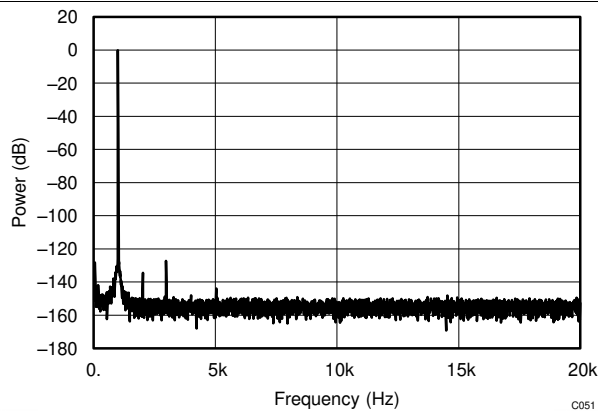


Figure 53. Output Voltage Spectrum (OPAx325)

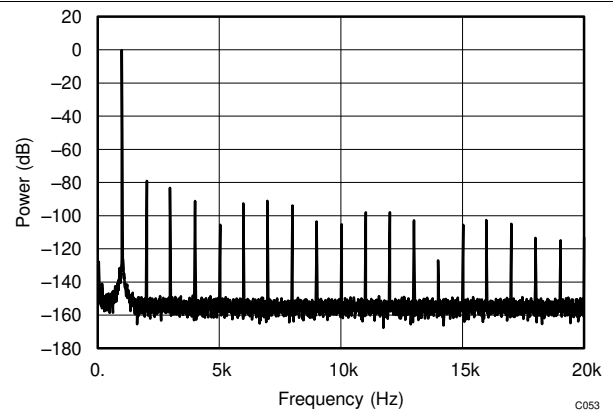


Figure 54. Output Voltage Spectrum (Typical CMOS Rail-to-Rail Amplifier)

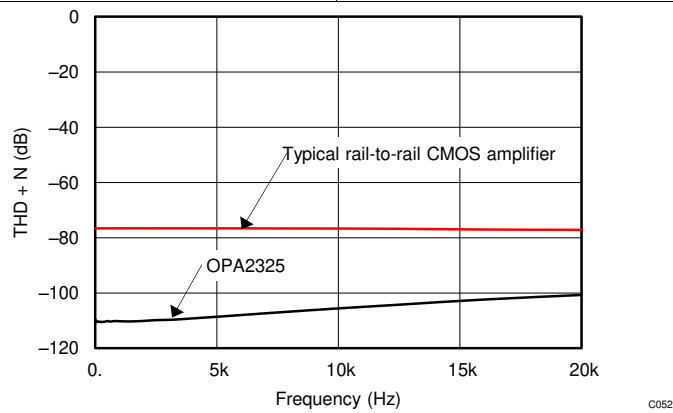


Figure 55. THD+N vs Frequency

## 9 Power Supply Recommendations

The OPAx325 are specified for operation from 2.2 V to 5.5 V ( $\pm 1.1$  V to  $\pm 2.75$  V); many specifications apply from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ . Parameters that can exhibit significant variance with regard to operating voltage or temperature are presented in the [Typical Characteristics](#) section.

## 10 Layout

### 10.1 Layout Guidelines

For best operational performance of the device, use good printed circuit board (PCB) layout practices, including:

- Noise can propagate into analog circuitry through the power pins of the circuit as a whole and of op amp itself. Bypass capacitors are used to reduce the coupled noise by providing low-impedance power sources local to the analog circuitry.
  - Connect low-ESR, 0.1- $\mu\text{F}$  ceramic bypass capacitors between each supply pin and ground, placed as close as possible to the device. A single bypass capacitor from V+ to ground is applicable for single-supply applications.
- Separate grounding for analog and digital portions of circuitry is one of the simplest and most-effective methods of noise suppression. One or more layers on multilayer PCBs are usually devoted to ground planes. A ground plane helps distribute heat and reduces electromagnetic interference (EMI) noise pickup. Make sure to physically separate digital and analog grounds, paying attention to the flow of the ground current. For more detailed information refer to, see [Circuit Board Layout Techniques](#).
- In order to reduce parasitic coupling, run the input traces as far away as possible from the supply or output traces. If these traces cannot be kept separate, crossing the sensitive trace perpendicular is much better as opposed to in parallel with the noisy trace.
- Place the external components as close as possible to the device. As illustrated in [Figure 57](#), keeping RF and RG close to the inverting input minimizes parasitic capacitance.
- Keep the length of input traces as short as possible. Always remember that the input traces are the most sensitive part of the circuit.
- Consider a driven, low-impedance guard ring around the critical traces. A guard ring can significantly reduce leakage currents from nearby traces that are at different potentials.
- For best performance, clean the PCB following board assembly.
- Any precision integrated circuit can experience performance shifts resulting from moisture ingress into the plastic package. Following any aqueous PCB cleaning process, baking the PCB assembly is recommended to remove moisture introduced into the device packaging during the cleaning process. A low-temperature, post-cleaning bake at  $85^{\circ}\text{C}$  for 30 minutes is sufficient for most circumstances.

## 10.2 Layout Example

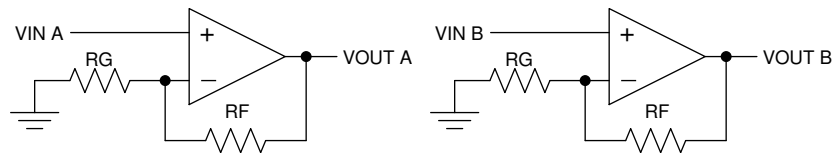


Figure 56. Schematic Representation for Figure 57

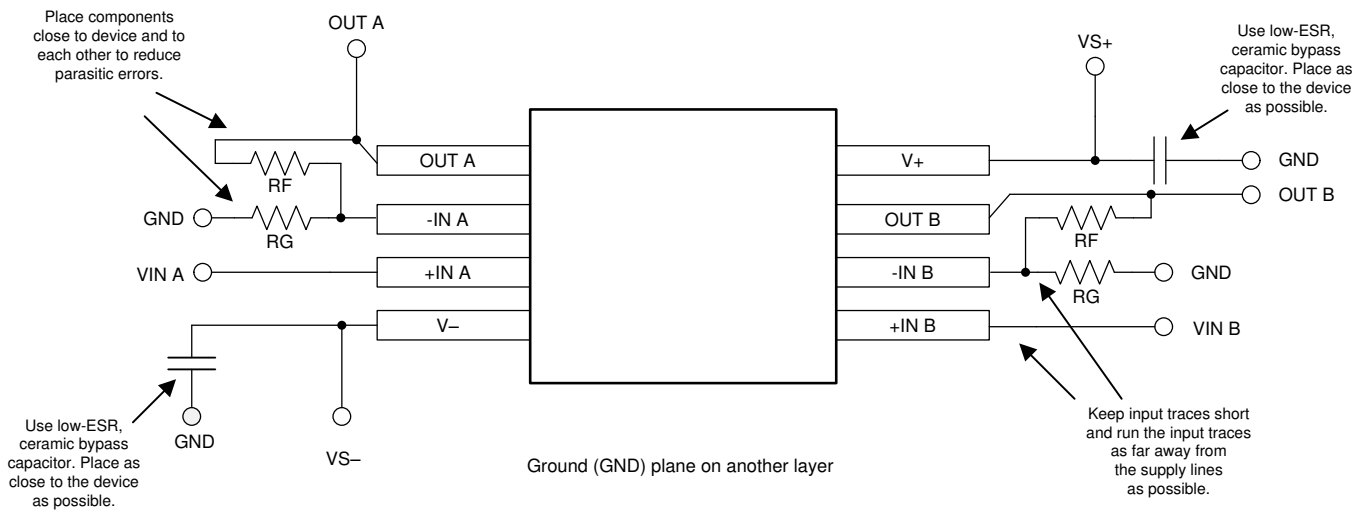


Figure 57. Layout Example

## 11 デバイスおよびドキュメントのサポート

### 11.1 ドキュメントのサポート

#### 11.1.1 関連資料

関連資料については、以下を参照してください。

テキサス・インスツルメンツ、『[Circuit Board Layout Techniques](#)』アプリケーション・レポート (英語)

### 11.2 関連リンク

表 1 に、クイック・アクセス・リンクの一覧を示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびご注文へのクイック・アクセスが含まれます。

表 1. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
OPA325	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>
OPA2325	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>
OPA4325	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>	<a href="#">ここをクリック</a>

### 11.3 ドキュメントの更新通知を受け取る方法

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### 11.4 コミュニティ・リソース

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](#), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 11.5 商標

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### 11.6 静電気放電に関する注意事項



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静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

### 11.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 12 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">OPA2325ID</a>	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
OPA2325ID.B	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
<a href="#">OPA2325IDGKR</a>	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU   SN	Level-2-260C-1 YEAR	-40 to 125	18L6
OPA2325IDGKR.B	Active	Production	VSSOP (DGK)   8	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	18L6
<a href="#">OPA2325IDGKT</a>	Active	Production	VSSOP (DGK)   8	250   SMALL T&R	Yes	NIPDAU   SN   NIPDAUAG	Level-2-260C-1 YEAR	-40 to 125	18L6
OPA2325IDGKT.B	Active	Production	VSSOP (DGK)   8	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	18L6
<a href="#">OPA2325IDR</a>	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
OPA2325IDR.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
OPA2325IDRG4	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
OPA2325IDRG4.B	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	O2325
<a href="#">OPA325IDBVR</a>	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
OPA325IDBVR.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
OPA325IDBVRG4	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
OPA325IDBVRG4.B	Active	Production	SOT-23 (DBV)   5	3000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
<a href="#">OPA325IDBVT</a>	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
OPA325IDBVT.B	Active	Production	SOT-23 (DBV)   5	250   SMALL T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	1UEV
<a href="#">OPA4325IPW</a>	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	4325
OPA4325IPW.B	Active	Production	TSSOP (PW)   14	90   TUBE	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	4325
<a href="#">OPA4325IPWR</a>	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	4325
OPA4325IPWR.B	Active	Production	TSSOP (PW)   14	2000   LARGE T&R	Yes	NIPDAU	Level-2-260C-1 YEAR	-40 to 125	4325

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

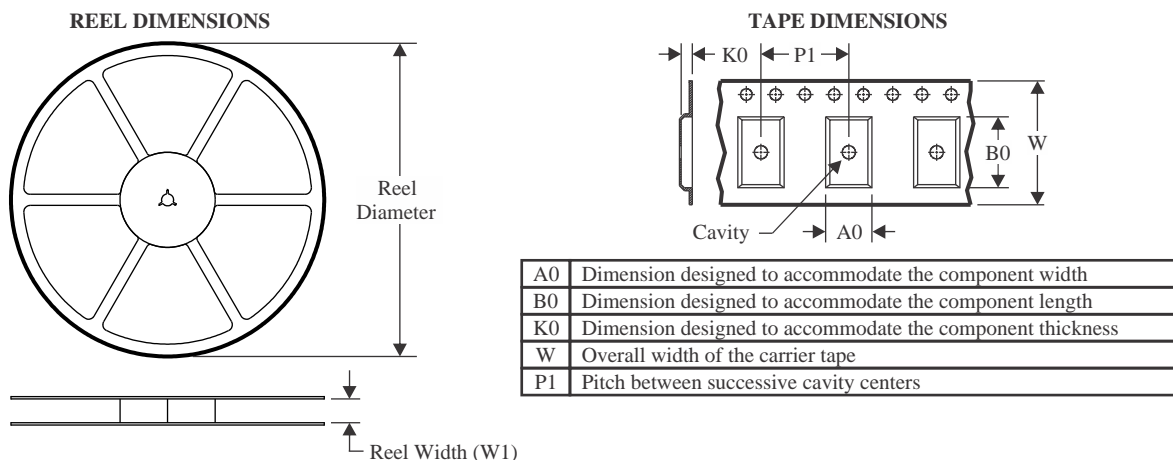
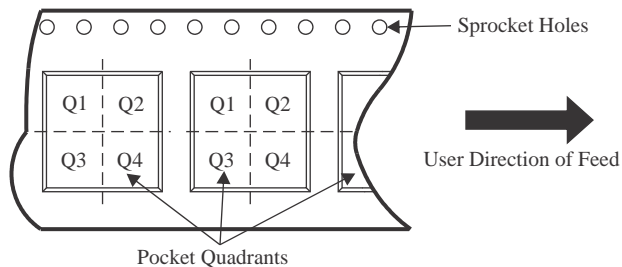
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


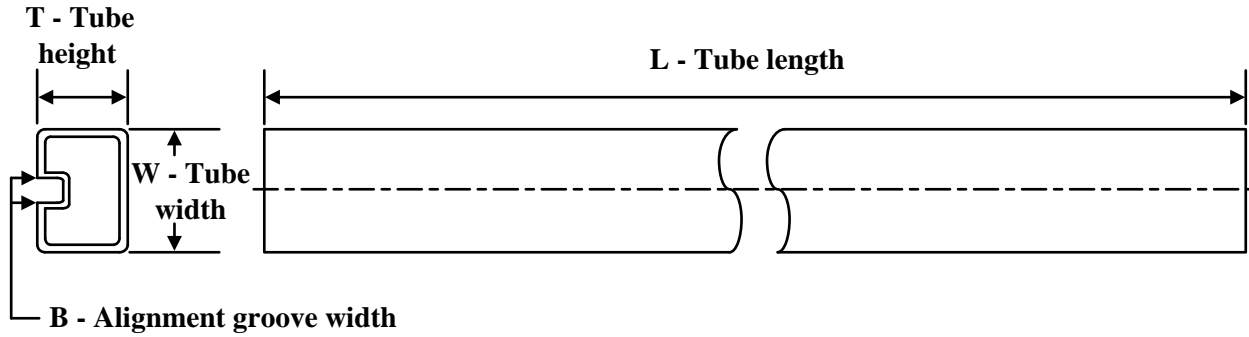
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
OPA2325IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.3	3.4	1.4	8.0	12.0	Q1
OPA2325IDGKR	VSSOP	DGK	8	2500	330.0	12.4	5.25	3.35	1.25	8.0	12.0	Q1
OPA2325IDGKT	VSSOP	DGK	8	250	330.0	12.4	5.25	3.35	1.25	8.0	12.0	Q1
OPA2325IDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA2325IDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
OPA325IDBVR	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA325IDBVRG4	SOT-23	DBV	5	3000	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA325IDBVT	SOT-23	DBV	5	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
OPA4325IPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
OPA2325IDGKR	VSSOP	DGK	8	2500	353.0	353.0	32.0
OPA2325IDGKR	VSSOP	DGK	8	2500	366.0	364.0	50.0
OPA2325IDGKT	VSSOP	DGK	8	250	366.0	364.0	50.0
OPA2325IDR	SOIC	D	8	2500	353.0	353.0	32.0
OPA2325IDRG4	SOIC	D	8	2500	353.0	353.0	32.0
OPA325IDBVR	SOT-23	DBV	5	3000	213.0	191.0	35.0
OPA325IDBVRG4	SOT-23	DBV	5	3000	213.0	191.0	35.0
OPA325IDBVT	SOT-23	DBV	5	250	213.0	191.0	35.0
OPA4325IPWR	TSSOP	PW	14	2000	353.0	353.0	32.0

**TUBE**


\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
OPA2325ID	D	SOIC	8	75	506.6	8	3940	4.32
OPA2325ID.B	D	SOIC	8	75	506.6	8	3940	4.32
OPA4325IPW	PW	TSSOP	14	90	530	10.2	3600	3.5
OPA4325IPW.B	PW	TSSOP	14	90	530	10.2	3600	3.5



D0008A

# PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

## NOTES:

- Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
- This drawing is subject to change without notice.
- This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed  $.006$  [0.15] per side.
- This dimension does not include interlead flash.
- Reference JEDEC registration MS-012, variation AA.

# EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE  
 EXPOSED METAL SHOWN  
 SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE  
BASED ON .005 INCH [0.125 MM] THICK STENCIL  
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

PW0014A



**PACKAGE OUTLINE**  
**TSSOP - 1.2 mm max height**

SMALL OUTLINE PACKAGE



NOTES:

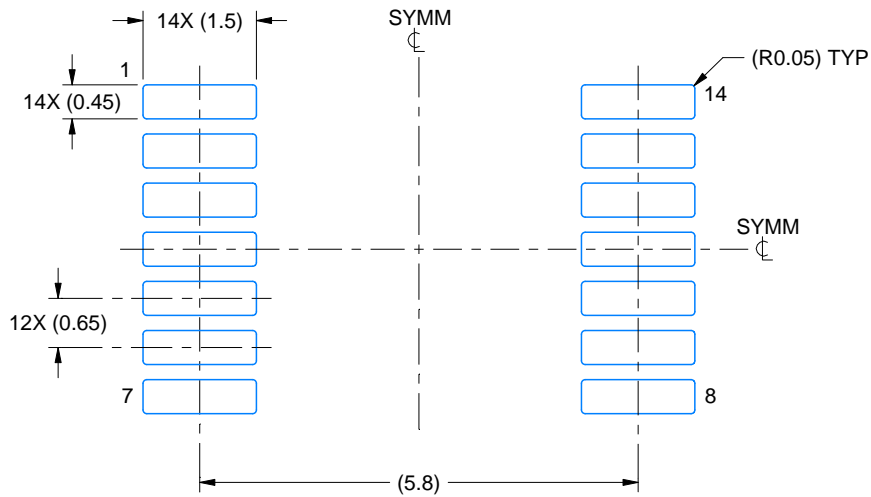
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220202/B 12/2023

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

PW0014A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220202/B 12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.





# EXAMPLE STENCIL DESIGN

DBV0005A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214839/K 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

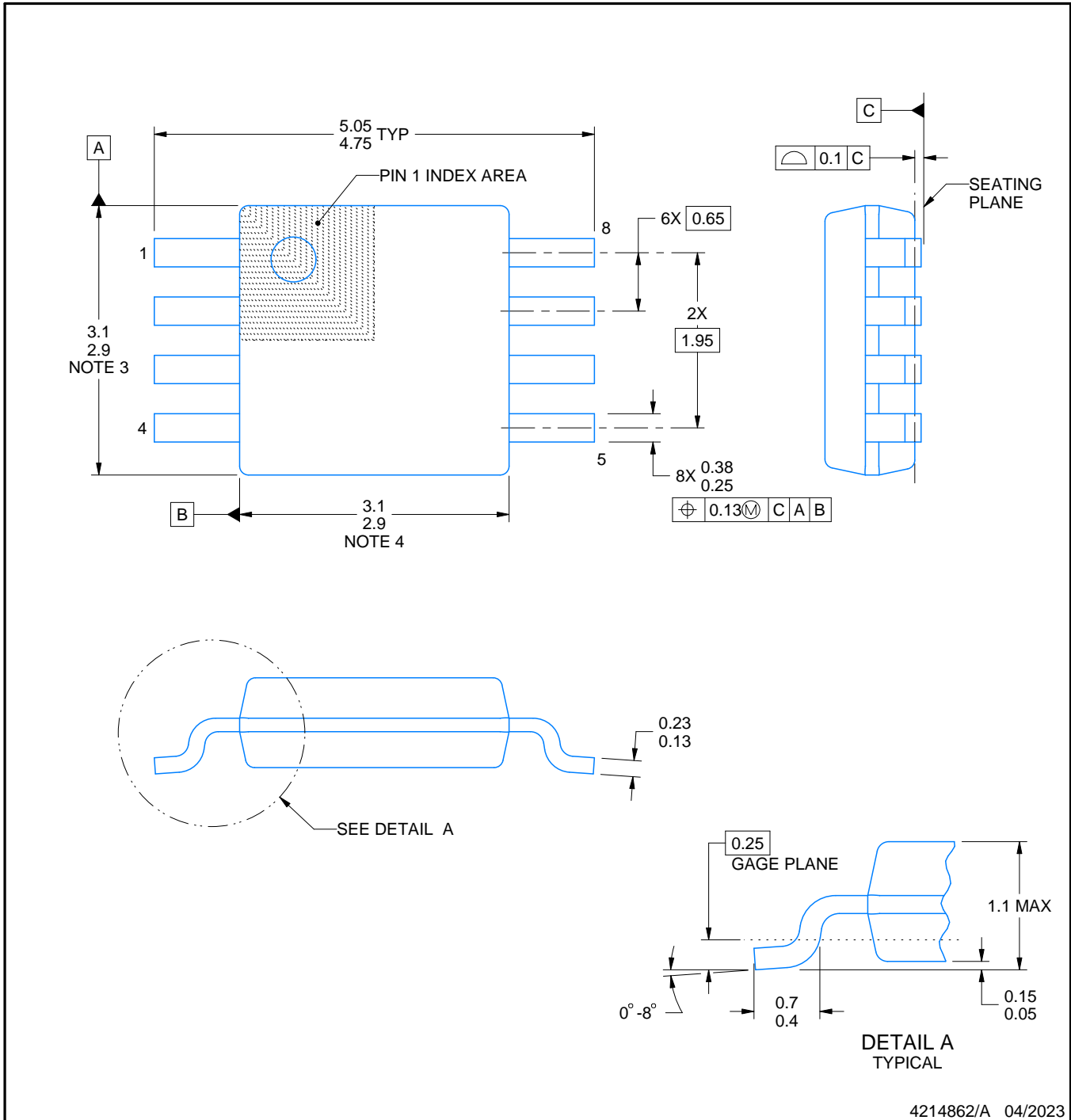
# DGK0008A



# PACKAGE OUTLINE

## VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



4214862/A 04/2023

**NOTES:**

PowerPAD is a trademark of Texas Instruments.

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-187.

# EXAMPLE BOARD LAYOUT

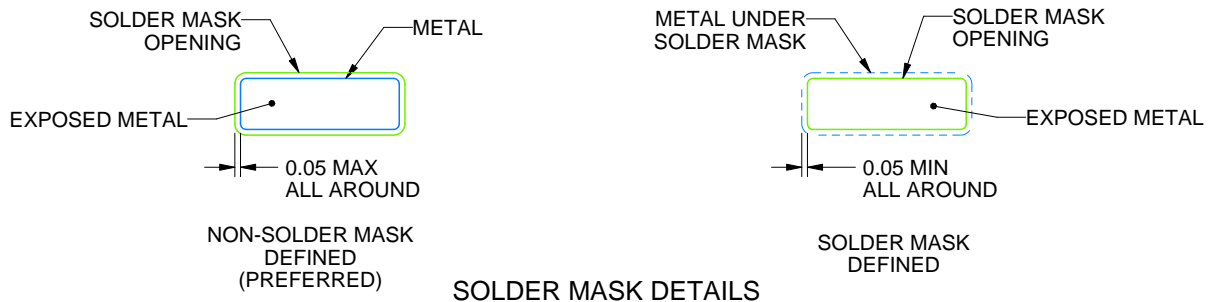
DGK0008A

™ VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 15X



SOLDER MASK DETAILS

4214862/A 04/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
8. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.
9. Size of metal pad may vary due to creepage requirement.

# EXAMPLE STENCIL DESIGN

DGK0008A

<sup>TM</sup> VSSOP - 1.1 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
SCALE: 15X

4214862/A 04/2023

NOTES: (continued)

11. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
12. Board assembly site may have different recommendations for stencil design.

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最終更新日 : 2025 年 10 月